

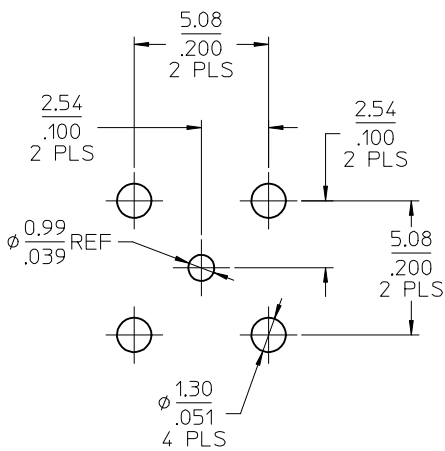
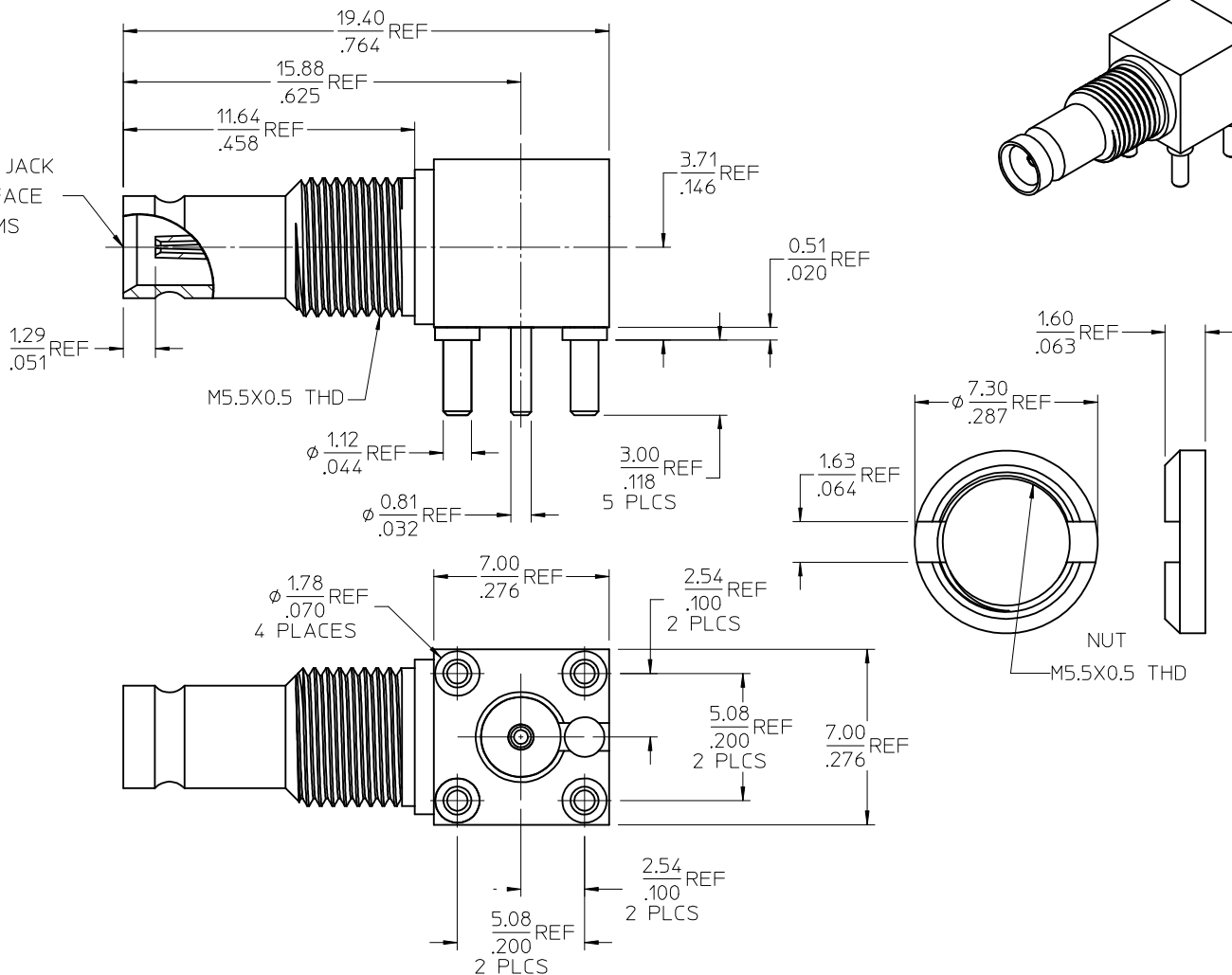
MATERIALS AND FINISHES

BODY, PIN, RETAINING RING, NUT: BRASS
PLATED: SEE TABLE

CONTACT: PHOSPHOR BRONZE
PLATED: GOLD (10μ-in MIN) OVER
NICKEL (100μ-in MIN)

INSULATOR: PTFE

1.0/2.3 JACK
INTERFACE
50 OHMS



RECOMMENDED HOLE LAYOUT

PS-89675-3450	PRODUCT SPECIFICATION
CECC 22 230	INTERFACE
SPECIFICATION	DESCRIPTION

73174-0411	GOLD (5μ-in MIN) OVER NICKEL (50μ-in MIN)
73174-0410	NICKEL (70μ-in MIN)
PART NO.	PLATING

CHG: UPDATE VIEWS FOR BODY AND POST CHANGES. ADD PLATING THICKNESS TO MATERIAL AND FINISH BLOCK/TABLE. ADD Ø1.78 4 PLACES DIM. ADD CUTAWAY VIEW AND 1.29 REF DIM. DEL MACHING NOTE.

EC NO: URF2017-0075
2016/08/09
DRW: MEIER
2016/08/10
CHKD: SSS
2016/08/16
APPR: ROBERTSON
DESCRIPTION

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---

ANGULAR ± 2 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM/IN

SCALE

DESIGN UNITS
METRIC

THIRD ANGLE PROJECTION

DRAWN BY
SSS
DATE
2004/03/02

CHECKED BY
TEF
DATE
2004/03/02

APPROVED BY
GMH
DATE
2004/03/02

MATERIAL NO.
SEE TABLE

SIZE
C

TITLE
1.0/2.3 JACK, R/A PCB
50 OHMS, EWR-2361
1.0/2.3-J/PCB

MOLEX INCORPORATED

DOCUMENT NO.
SD-73174-041

SHEET NO.
1 OF 1

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